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Sheet 1

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Cor	nplete if Known
Application Number	10/730,388
Filing Date	December 07, 2003
First Named Inventor	Buxton, et al.
Art Unit	2863
Examiner Name	Khuu, Cindy D.
Attorney Docket Number	TAI 0800

U. S. PATENT DOCUMENTS Pages, Columns, Lines, Where Name of Patentee or **Publication Date Document Number** MM-DD-YYYY Applicant of Cited Document Relevant Passages or Relevant Initials* Figures Appear Number-Kind Code2 (F known) US- 5,240,866 Curl Friedman et al. 08-31-1993 ^{US-} 5.787,190 07-28-1998 Peng et al. US- 6,477,685 11-05-2002 Lovelace ^{US-} 6,516,309 02-04-2003 CARL Eberhart US-US-US-US-US-UŞ-US-USus-US-US-US-US-

		FORE	GN PATENT DOCU	MENTS		
Examiner Initials*	Cite No.1	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear	l r°
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Examiner Considered Signature

Signature Chock Khuu*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation is in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation is in conformance and not *EXAMINER: Initial if reference considered, whether or not citation is in conformance and initial initia EXAMINER: Initial if retgrence considered, whether or not clauon is in conformance with MPEP 605. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. Applicant's unique citation designation number (optional). See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. Skind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. Applicant is to place a check mark here if English language

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Substitute for form 1449/PTO		Complete if Known
	Application Number	10/730,388
INFORMATION DISCLOSURE	Filing Date	December 07, 2003
STATEMENT BY APPLICANT	First Named Inventor	Buxton, et al.
	Art Unit	2863
(Use as many sheets as necessary)	Examiner Name	Khuu, Cindy D.
Sheet 2 of 5	Attorney Docket Number	TAI.0800

. 		NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T2
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		SINGH, Position Statement: Good Die in Bad Neighborhoods, IEEE	
		MILLER, Position Statement: Good Die in Bad Neighborhoods, IEEE	
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CIAL		CHEN, et al., A Neural-Network Approach to Recognize Defect Spatial Pattern in Semiconductor Fabrication, IEEE	

Examiner Signature	Cindy	Khure	Date Considered	12-11-06

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Sheet	3	l of l	5	Attorney Docket Number	TAI.0800	

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CALL		Advance Parametric Tester with HP SPECS, Hewlett-Packard Company, 1999	

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Examiner	0,1	1/1	Date	12-11-06
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Signature Considered 72 // 00	 Cinda	Khun	 nte onsidered	12-11-06

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